

Product Change Notification - CYER-22LSUP207

Date:	19 Dec 2011
Product Category:	16-bit Microcontrollers and Digital Signal Controllers; 32-bit PIC Microcontrollers
Device Family:	
Notification subject:	CCB 1066 Final Notice: Qualification of 121L XBGA (10x10) with DS7409HGB substrate at ANAP assembly site.
Notification text:	PCN Status: Final notification Microchip Parts Affected: See attachments of affected catalog part numbers (CPN) labeled as PCN_CYER-22LSUP207_Affected_CPN.xls
	PCN_CYER-22LSUP207_Affected_CPN.pdf
	Description of Change: Qualification of 121L XBGA (10x10) with DS7409HGB substrate at ANAP assembly site.
	Pre Change: CCL-HL832NX substrate
	Post Change: DS7409HGB substrate
	Impacts to Data Sheet: None
	Reason for Change: To improve on time delivery performance
	Change Implementation Status: In Progress
	Estimated First Ship Date: January 31, 2012 (date code: 1206)
	NOTE: Please be advised that during the transition period customers may receive pre and post change parts, due to existing inventory of the pre changed parts.
	Markings to Distinguish Revised from Unrevised Devices: Traceability code
	Revision History: June 28, 2011: Issued initial notification. December 19, 2011: Issued final notification. Attached qualification data. Revised the estimated first ship date from 9/30/2011 to 1/31/2012.
Attachment(s):	PCN_CYER-22LSUP207_Affected_CPN.pdf PCN_CYER-22LSUP207_Affected_CPN.xls PCN_CYER-22LSUP207_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at http://www.microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to <u>microchipDIRECT</u> and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

CYER-22LSUP207 - CCB 1066 Final Notice: Qualification of 121L XBGA (10x10) with DS7409HGB substrate at ANAP assembly site.

Parts Affected

PIC24FJ128DA210 PIC24FJ256GB210 PIC32MX320F128L PIC32MX340F128L PIC32MX360F256L PIC32MX360F512L PIC32MX440F128L PIC32MX460F256L PIC32MX460F512L PIC32MX534F064L PIC32MX564F064L PIC32MX564F128L PIC32MX575F256L PIC32MX575F512L PIC32MX664F064L PIC32MX664F128L PIC32MX675F256L PIC32MX675F512L PIC32MX695F512L PIC32MX764F128L PIC32MX775F256L PIC32MX775F512L PIC32MX795F512L